

In the Claims:

Please cancel claims 40, 42, 47, 48, 50-53, 56, and 61-64 without prejudice.

Please amend claims 41, 43-46, 49, 54, 55, and 57-60 to read as follows:

41. (Amended) The electronic component of claim 65, wherein the main body region comprises a curved portion.

43. (Amended) The electronic component of claim 65 wherein the main body region is approximately parallel to a surface of the electronic component.

44. (Amended) The electronic component of claim 65 wherein at least a portion of the main body region is displaced from the substrate by a distance of between about 5 and 200 mils (thousandths of an inch).

45. (Amended) The electronic component of claim 65 wherein at least a portion of the main body region is displaced from the substrate by a distance of between about 2 and 8 mils.

46. (Amended) The electronic component of claim 65, wherein said contact structure further comprises a sloped region disposed between the base region and the main body region .

49. (Amended) The electronic component of claim 46 where the sloped region has an average angle of between about 60 and about 75 degrees.

54. (Amended) The electronic component of claim 65 wherein the conductive material comprises nickel.

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55. (Amended) The electronic component of claim 65 wherein the conductive material comprises a material selected from the group consisting of nickel, copper, cobalt, iron, gold, silver, elements of the platinum group, noble metals, semi-noble metals, elements of the palladium group, tungsten, and molybdenum

57. (Amended) The electronic component of claim 65 wherein the substrate comprises a semiconductor device.

58. (Amended) The electronic component of claim 65 wherein the substrate comprises a semiconductor device that has been singulated from a wafer.

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59. (Amended) The electronic component of claim 65 wherein the substrate comprises a device selected from the group consisting of a semiconductor device, a memory device, a portion of a semiconductor wafer, a space transformer, a ceramic device, a probe card, a chip carrier and a socket.

60. (Amended) The electronic component of claim 65 further comprising a separate tip structure joined permanently to the contact structure.

**Please add new claims 65-70 as follows:**

65. (New) An electronic component comprising:

    a substrate including a conductive area;

    masking material formed on said substrate, said masking material patterned to form an opening corresponding to at least a portion of said conductive area and a main body portion;

    conductive material deposited on said masking material within said opening and on said main body portion, said conductive material composing a contact structure comprising:

        a base region electrically connected to said conductive area and formed within said opening, and

        a main body region formed on said main body portion of said masking material, said main body region being integrally formed with said base region and displaced away from said substrate.

66. (New) The electronic component of claim 65, wherein said masking material comprises a plurality of masking layers.

67. (New) The electronic component of claim 65, wherein said opening is tapered.

68. (New) The electronic component of claim 65, wherein said conductive area comprises a terminal on a surface of said substrate.

69. (New) The electronic component of claim 65 further comprising a terminal on a surface of said substrate, said terminal being electrically connected to said conductive area.

70. (New) An electronic component comprising:

a substrate including at least one conductive element;

conductive means for providing an electrical connection with at least one of said conductive elements of said substrate;

masking means for forming a patterned mold comprising an opening corresponding to at least a portion of said conductive means and a main body portion;

contact means for providing an electrical connection between said conductive means and a point displaced from said substrate, said contact means formed of a conductive material integrally deposited on said masking material means within said opening and on said main body portion, said contact means comprising:

a base region formed on said conductive means within said opening, and

a main body region formed on said main body portion of said masking means, said main body region being integrally formed with said base region and displaced away from said substrate.

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